



Click [here](#) for the 3D model.

Dimensions

Chip Size	1210
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
T	1.7mm +/-0.20mm
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	Waffle, Tray
Packaging Quantity	80

General Information

Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	70 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches.
Shelf Life	26 Weeks
MSL	1

Specifications

Capacitance	0.15 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	6.6667 GOhms